



VMDSEMI

**VFTL010R750NA**

**Datasheet**



VMDSEMI

## General Description

## Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	$I_D$
100V	75mΩ@10V	15A
	90mΩ@4.5V	

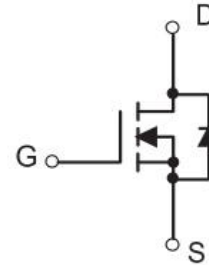


Figure 1 Symbol of VFTL010R750NA

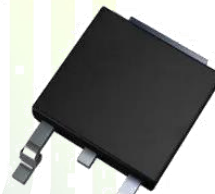
## Features

- Low  $R_{DS(ON)}$  & FOM
- Extremely low switching loss
- Excellent reliability and uniformity
- Fast switching and soft recovery

## Application

- PD charger
- Motor driver
- Switching voltage regulator
- DC-DC converter
- Switched mode power supply

## Package Type



**TO-252**

Figure 2 Package Type of VFTL010R750NA

## Ordering Information

Product Name	Package
VFTL010R750NA	TO-252

**Absolute Maximum Ratings** ( $T_J = 25\text{ °C}$ , unless otherwise specified)

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		$V_{DSS}$	100	V
Gate-Source Voltage		$V_{GSS}$	$\pm 20$	V
Continuous Drain Current <sup>Note1</sup>	$T_C = 25\text{ °C}$	$I_D$	15	A
Pulsed Drain Current <sup>Note2</sup>	$T_C = 25\text{ °C}$	$I_{DM}$	45	
Continuous diode forward current <sup>Note1</sup>	$T_C = 25\text{ °C}$	$I_S$	15	
Diode pulsed current <sup>Note2</sup>	$T_C = 25\text{ °C}$	$I_{S,PULSE}$	45	
Single Pulsed Avalanche Energy <sup>Note5</sup>		$E_{AS}$	5.5	mJ
Total Power Dissipation <sup>Note3</sup>	$T_C = 25\text{ °C}$	$P_D$	36	W
Junction Temperature		$T_J$	150	°C
Storage Temperature		$T_{STG}$	-55 to 150	°C

**Thermal Resistance**

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient <sup>Note4</sup>	$R_{\theta JA}$		62		°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		3.5		°C/W

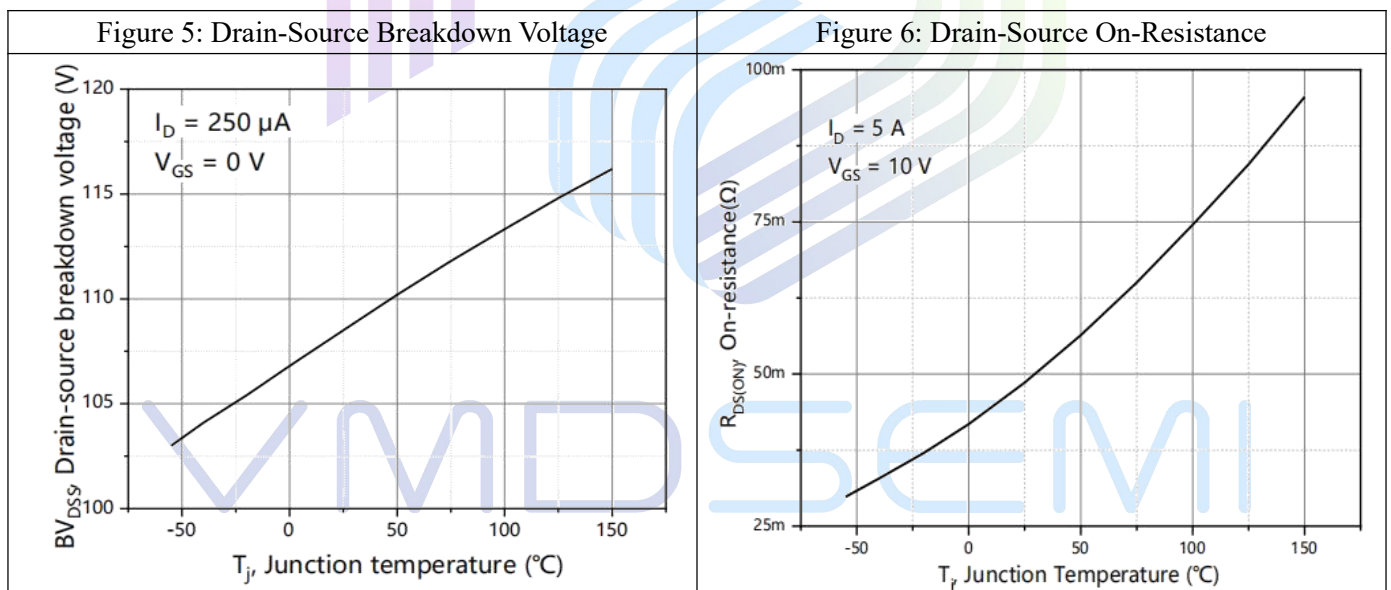
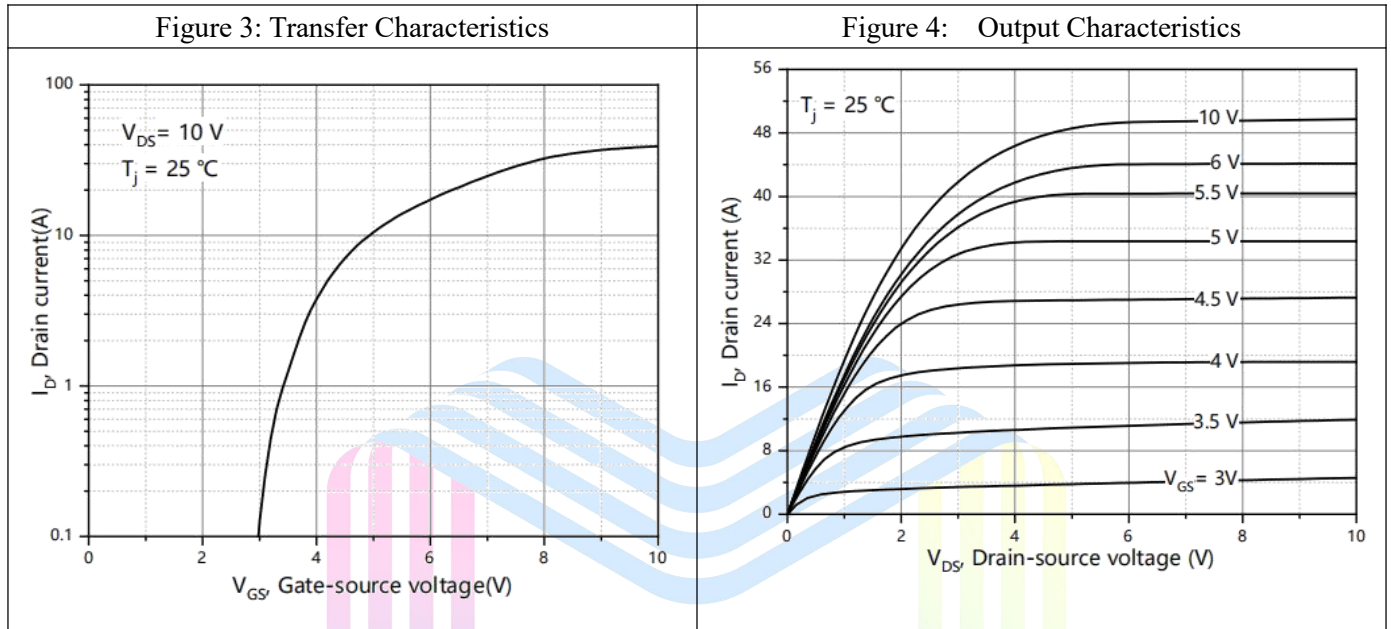
**Electrical Characteristics** ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

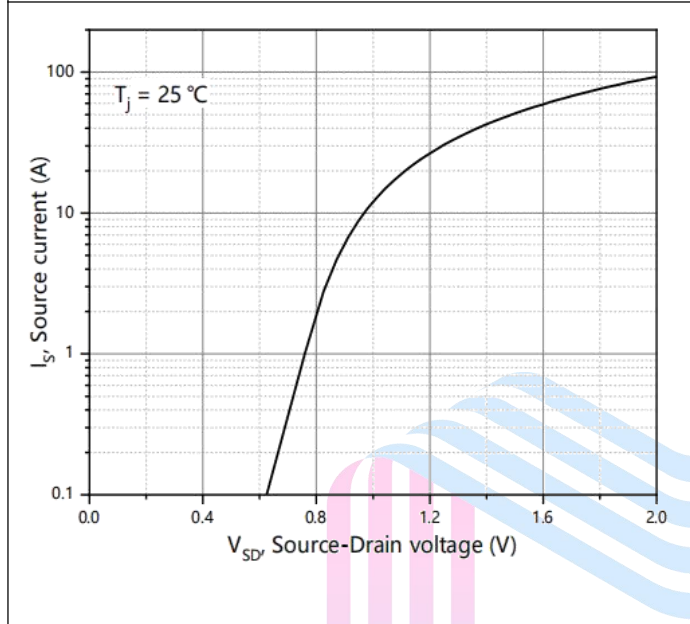
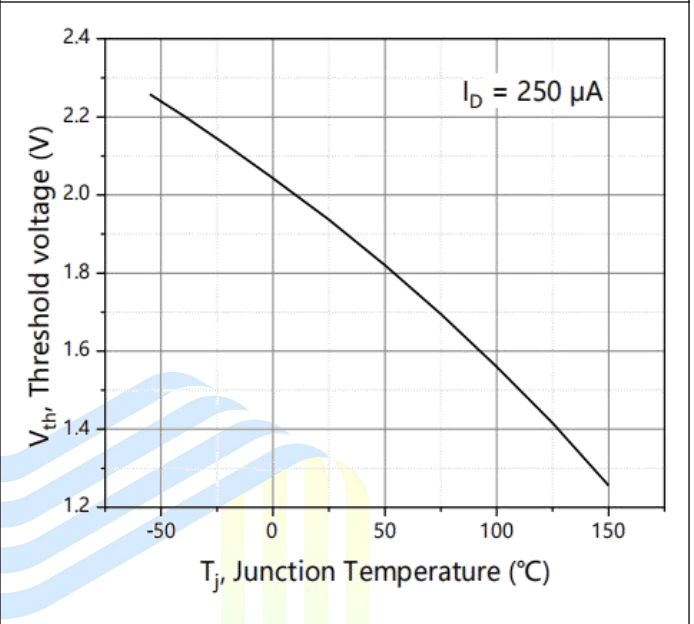
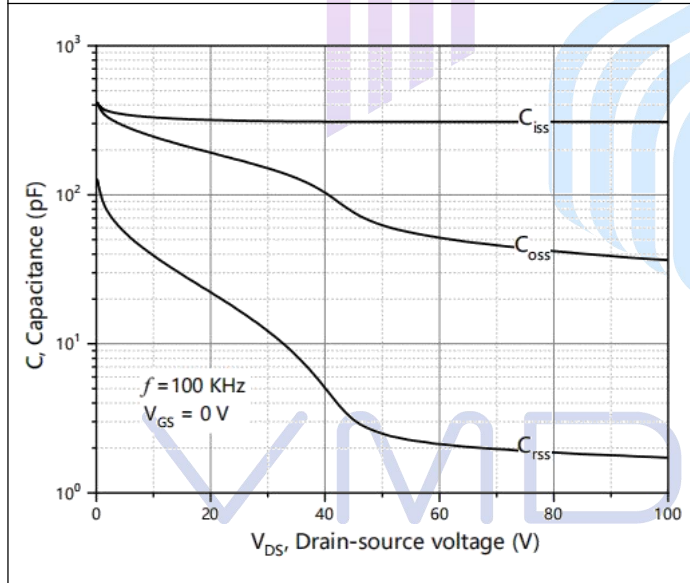
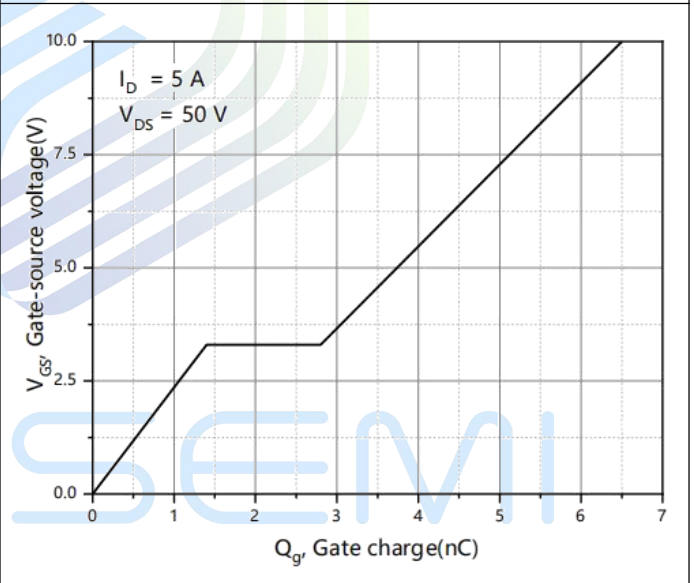
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	100			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=100V, V_{GS}=0V$			1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=20V, V_{DS}=0V$			100	nA
		$V_{GS}=-20V, V_{DS}=0V$			-100	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.2		2.5	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=5A$		50	75	mΩ
		$V_{GS}=4.5V, I_D=3A,$		60	90	
Gate Resistance	$R_g$	$f=1MHz, \text{Open Drain}$		28.8		Ω
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=25V$		310		pF
Output Capacitance	$C_{OSS}$	$V_{GS}=0V$		171		pF
Reverse Transfer Capacitance	$C_{RSS}$	$f=100KHz$		16.7		pF
Total Gate Charge	$Q_g$	$V_{DS}=50V$ $V_{GS}=10V$ $I_D=5A$		6.5		nC
Gate-Source Charge	$Q_{gs}$			1.4		
Gate-Drain Charge	$Q_{gd}$			1.4		
Gate plateau voltage	$V_{plateau}$			3.3		V
<b>Switching Parameters</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DS}=50V$		14		ns
Turn-on Rise Time	$t_r$	$V_{GS}=10V$		3.2		
Turn-off Delay Time	$t_{d(off)}$	$I_D=5A$		36		
Turn-off Fall Time	$t_f$	$R_G=2\Omega$		14		
<b>Diode Characteristics</b>						
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=7A$			1.3	V
Reverse Recovery Time	$t_{rr}$	$I_S=5A$		36		ns
Reverse Recovery Charge	$Q_{rr}$	$V_R=50V$		37		nC
Peak Reverse Recovery Current	$I_{rrm}$	$di/dt=100A/\mu s$		1.7		A

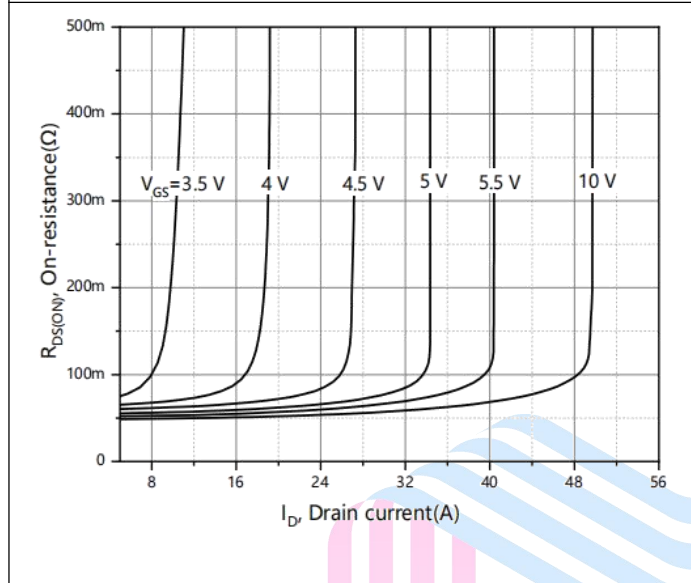
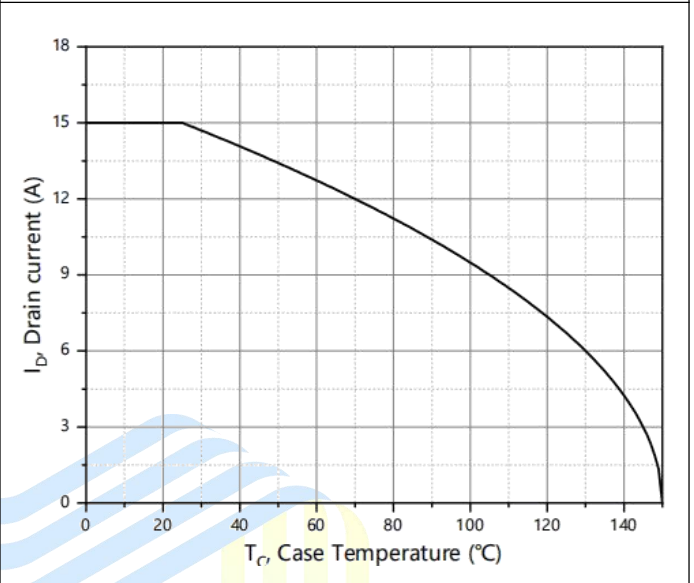
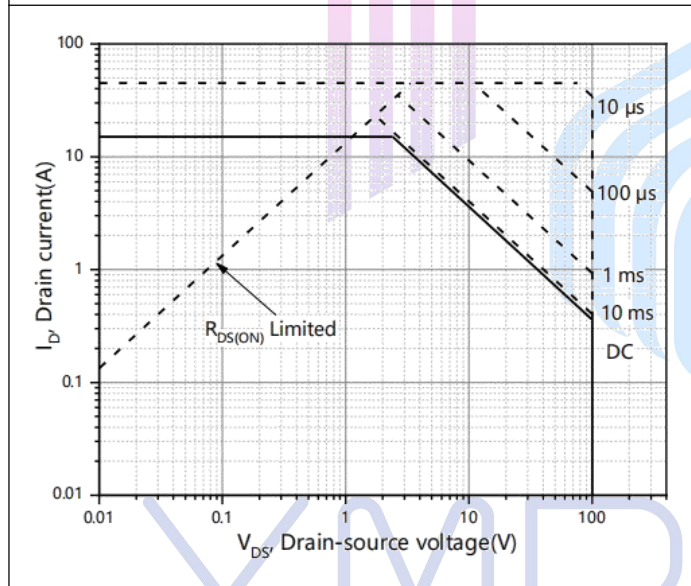
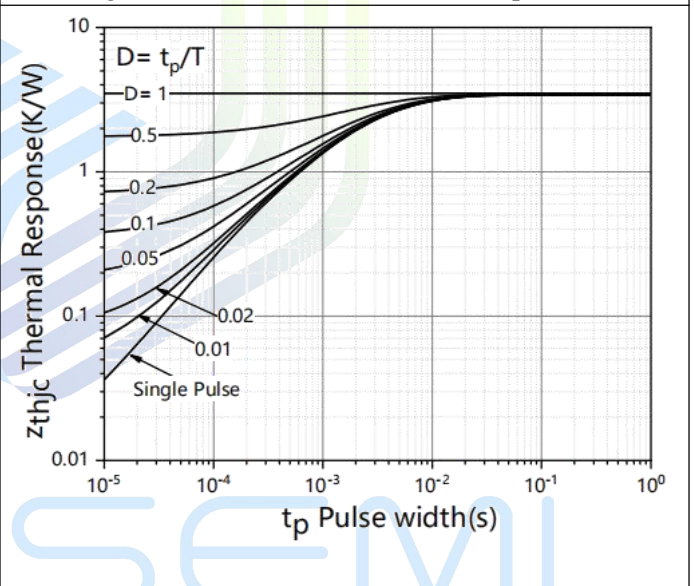
**Notes :**

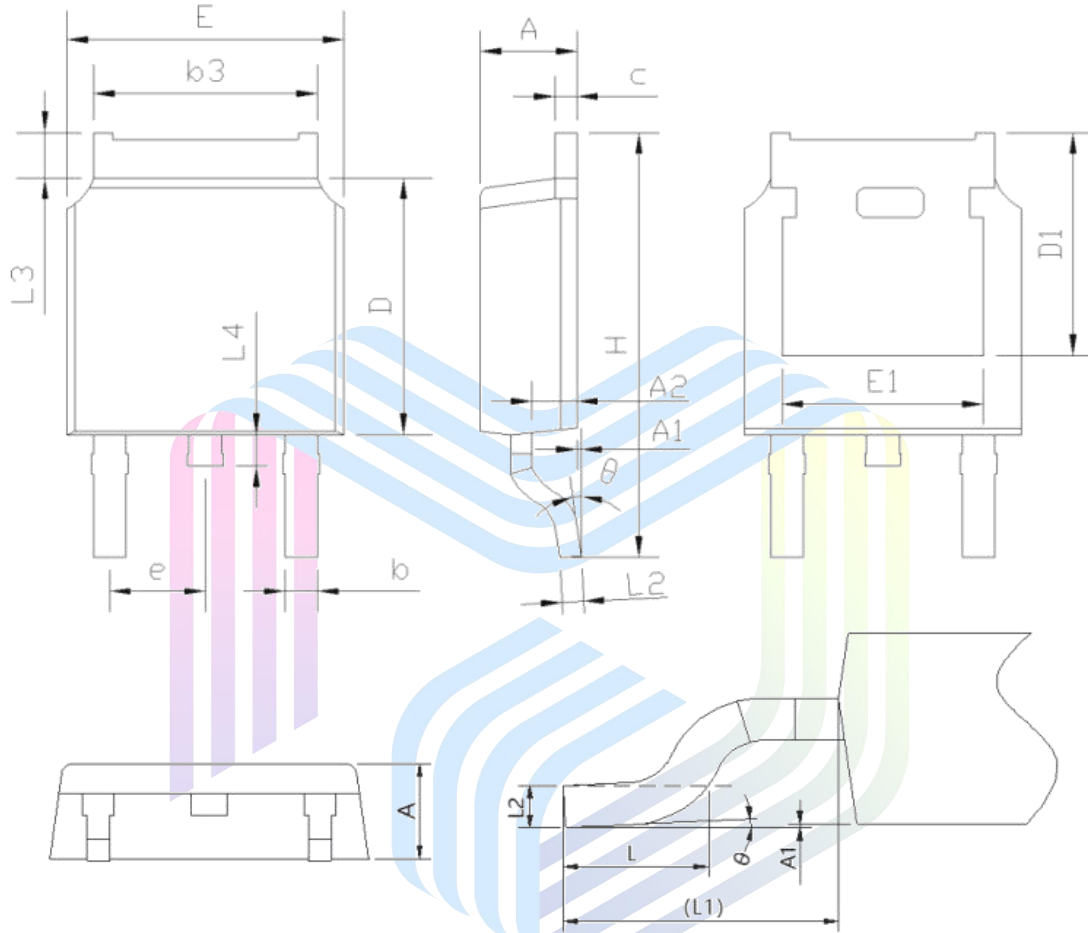
1. Calculated continuous current based on maximum allowable junction temperature.
2. Repetitive rating; pulse width limited by max. junction temperature.
3.  $P_D$  is based on max junction temperature, using junction-case thermal resistance.
4. The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz Copper, in a still air environment with  $T_A=25\text{ }^\circ\text{C}$ .
5.  $V_{DD}=30\text{ V}, V_{GS}=10\text{ V}, L=0.3\text{ mH}$ , starting  $T_J=25\text{ }^\circ\text{C}$ .

## Typical Performance Characteristics



**Figure 7: Body Diode Characteristics**

**Figure 8: Threshold Voltage**

**Figure 9: Typical Capacitance**

**Figure 10: Gate Charge**


**Figure 11: Drain-Source On-Resistance**

**Figure 12: Drain Current**

**Figure 13: Safe operation area  $T_C=25^{\circ}C$** 

**Figure 13: Max. transient thermal impedance**


**Mechanical Dimensions:**
**TO-252 Package Information**


Symbol	mm		
	Min	Nom	Max
A	2.20	2.30	2.38
A1	0.00	-	0.20
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b3	5.20	5.33	5.46
c	0.43	0.53	0.61
D	5.98	6.10	6.22
D1	5.30 REF		
E	6.40	6.60	6.73
E1	4.63	-	-
e	2.286 BSC		
H	9.40	10.10	10.50
L	1.38	1.50	1.75
L1	2.90 REF		
L2	0.51 BSC		
L3	0.88	-	1.28
L4	0.50	-	1.00
θ	0°	-	8°



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